



# PMEG4005EPK

40 V, 0.5 A low VF MEGA Schottky barrier rectifier

30 April 2020

Product data sheet

## 1. General description

Planar Maximum Efficiency General Application (MEGA) Schottky barrier rectifier with an integrated guard ring for stress protection, encapsulated in a leadless ultra small SOD1608 (DFN1608D-2) Surface-Mounted Device (SMD) plastic package with visible and solderable side pads.

## 2. Features and benefits

- Average forward current:  $I_{F(AV)} \leq 0.5$  A
- Reverse voltage:  $V_R \leq 40$  V
- Low forward voltage  $V_F \leq 590$  mV
- Low reverse current
- Solderable side pads
- Package height typ. 0.37 mm
- Ultra small and leadless SMD plastic package
- AEC-Q101 qualified

## 3. Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch mode power supply
- LED backlight for mobile application
- Low power consumption applications
- Ultra high-speed switching
- Reverse polarity protection

## 4. Quick reference data

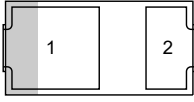

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$I_{F(AV)}$	average forward current	$\delta = 0.5$ ; square wave; $f = 20$ kHz; $T_{amb} \leq 115$ °C	-	-	0.5	A
		$\delta = 0.5$ ; square wave; $f = 20$ kHz; $T_{sp} \leq 140$ °C	-	-	0.5	A
$V_R$	reverse voltage	$T_j = 25$ °C	-	-	40	V
$V_F$	forward voltage	$I_F = 500$ mA; $t_p \leq 300$ $\mu$ s; $\delta \leq 0.02$ ; pulsed; $T_j = 25$ °C	-	530	590	mV
$I_R$	reverse current	$V_R = 10$ V; $T_j = 25$ °C	-	0.4	2	$\mu$ A
$t_{rr}$	reverse recovery time	$I_F = 0.5$ A; $I_R = 0.5$ A; $I_{R(meas)} = 0.1$ A; $T_j = 25$ °C	-	2	-	ns

[1] Device mounted on a ceramic Printed-Circuit Board (PCB),  $Al_2O_3$ , standard footprint.

## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode <sup>[1]</sup>	 <p>Transparent top view DFN1608D-2 (SOD1608)</p>	 sym001
2	A	anode		

[1] The marking bar indicates the cathode.

## 6. Ordering information

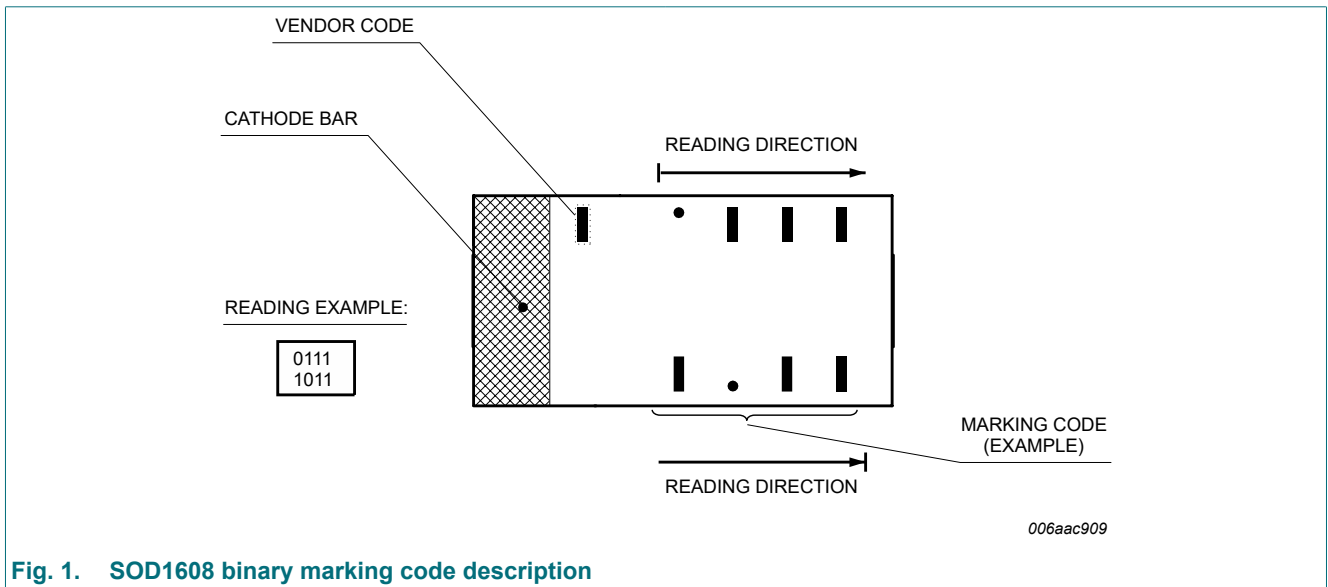
Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PMEG4005EPK	DFN1608D-2	plastic, leadless ultra small plastic package with side-wettable flanks (SWF); 2 terminals; 0.94 mm pitch; 1.6 mm x 0.8 mm x 0.37 mm body	SOD1608

## 7. Marking

Table 4. Marking codes

Type number	Marking code
PMEG4005EPK	0010 0000



## 8. Limiting values

**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit	
$V_R$	reverse voltage	$T_j = 25\text{ °C}$	-	40	V	
$I_F$	forward current	$T_{sp} \leq 135\text{ °C}$	-	0.7	A	
$I_{F(AV)}$	average forward current	$\delta = 0.5$ ; square wave; $f = 20\text{ kHz}$ ; $T_{amb} \leq 115\text{ °C}$	[1]	-	0.5	A
		$\delta = 0.5$ ; square wave; $f = 20\text{ kHz}$ ; $T_{sp} \leq 140\text{ °C}$		-	0.5	A
$I_{FRM}$	repetitive peak forward current	$t_p \leq 1\text{ ms}$ ; $\delta \leq 0.25$	-	2	A	
$I_{FSM}$	non-repetitive peak forward current	$t_p = 8\text{ ms}$ ; square wave; $T_{j(\text{init})} = 25\text{ °C}$	-	3	A	
$P_{tot}$	total power dissipation	$T_{amb} \leq 25\text{ °C}$	[2] [3]	-	390	mW
			[4] [3]	-	830	mW
			[1] [3]	-	1470	mW
$T_j$	junction temperature		-	150	°C	
$T_{amb}$	ambient temperature		-55	150	°C	
$T_{stg}$	storage temperature		-65	150	°C	

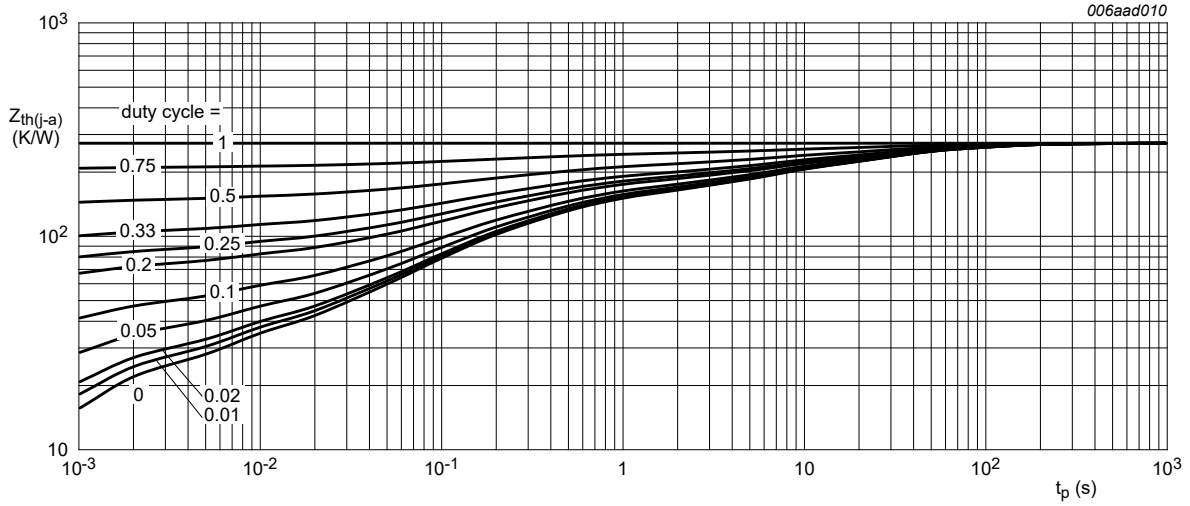
- [1] Device mounted on a ceramic Printed-Circuit Board (PCB),  $Al_2O_3$ , standard footprint.  
 [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.  
 [3] Reflow soldering is the only recommended soldering method.  
 [4] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode  $1\text{ cm}^2$ .

## 9. Thermal characteristics

**Table 6. Thermal characteristics**

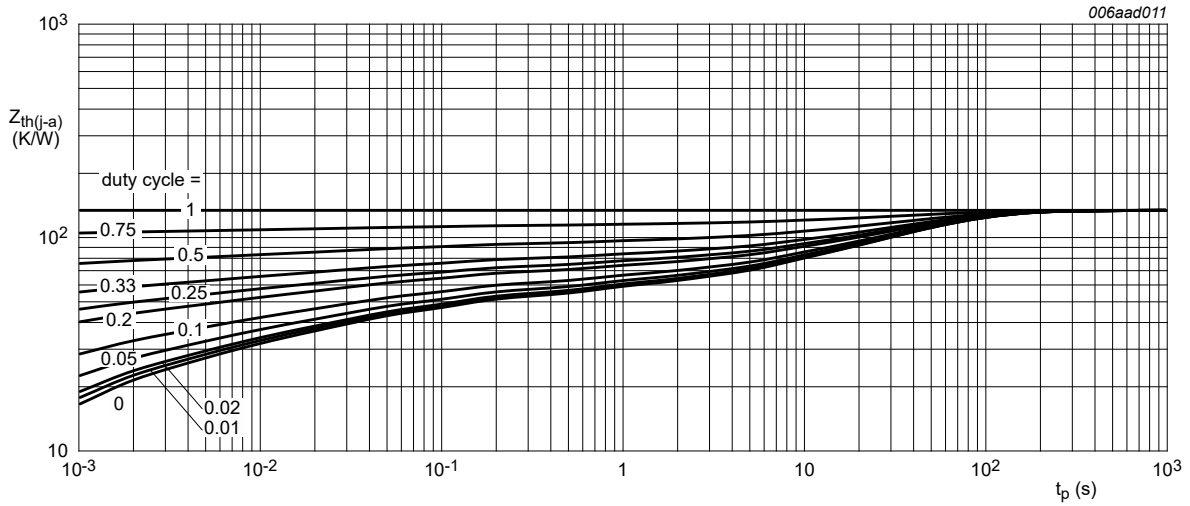
Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1] [2] [3]	-	-	320	K/W
			[1] [4] [3]	-	-	150	K/W
			[1] [5] [3]	-	-	85	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		[6]	-	-	20	K/W

- [1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses  $P_R$  are a significant part of the total power losses.  
 [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.  
 [3] Reflow soldering is the only recommended soldering method.  
 [4] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode  $1\text{ cm}^2$ .  
 [5] Device mounted on a ceramic PCB,  $Al_2O_3$ , standard footprint.  
 [6] Soldering point of cathode tab.



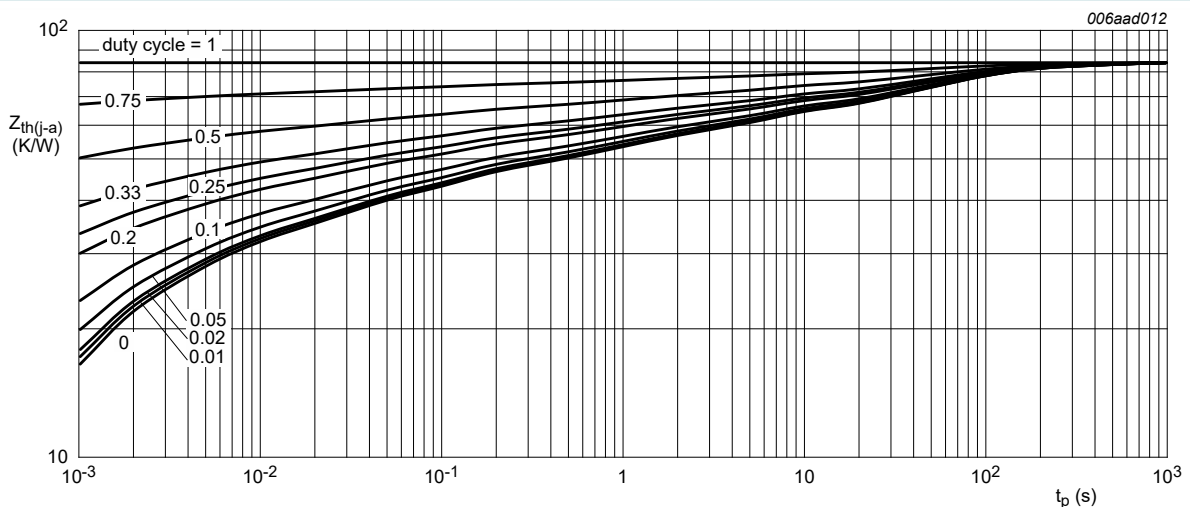
FR4 PCB, standard footprint

Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB, mounting pad for cathode 1 cm<sup>2</sup>

Fig. 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



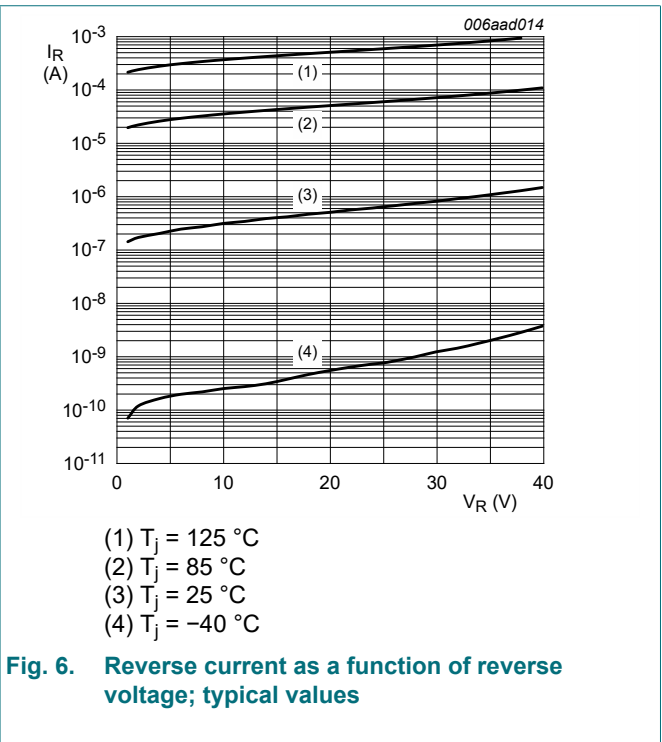
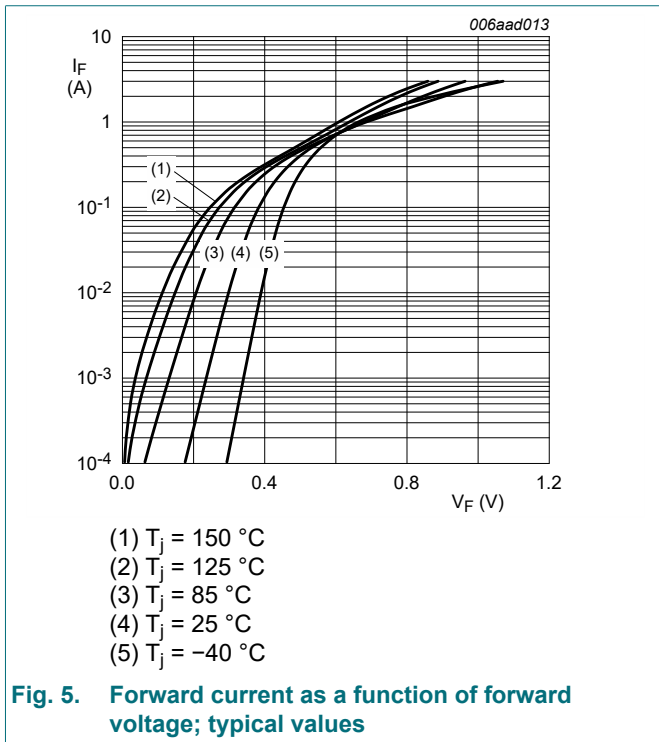
Ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint

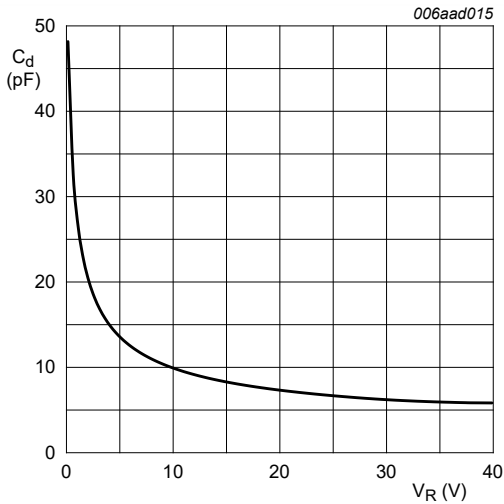
Fig. 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

## 10. Characteristics

Table 7. Characteristics

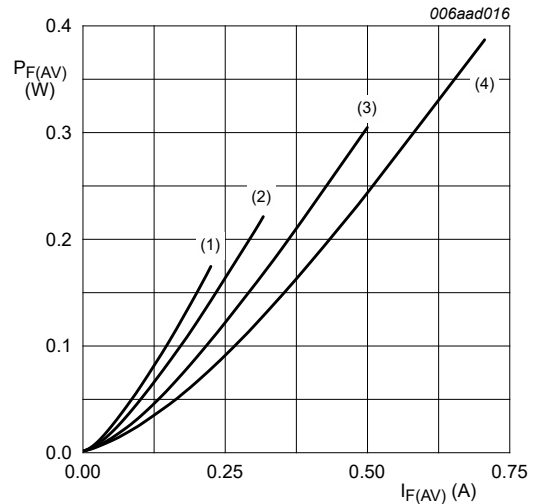
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_F$	forward voltage	$I_F = 100 \text{ mA}; t_p \leq 300 \text{ } \mu\text{s}; \delta \leq 0.02;$ pulsed; $T_j = 25 \text{ }^\circ\text{C}$	-	380	420	mV
		$I_F = 500 \text{ mA}; t_p \leq 300 \text{ } \mu\text{s}; \delta \leq 0.02;$ pulsed; $T_j = 25 \text{ }^\circ\text{C}$	-	530	590	mV
$I_R$	reverse current	$V_R = 10 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	-	0.4	2	$\mu\text{A}$
		$V_R = 40 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	-	2	10	$\mu\text{A}$
$C_d$	diode capacitance	$V_R = 1 \text{ V}; f = 1 \text{ MHz}; T_j = 25 \text{ }^\circ\text{C}$	-	30	35	pF
		$V_R = 10 \text{ V}; f = 1 \text{ MHz}; T_j = 25 \text{ }^\circ\text{C}$	-	10	15	pF
$t_{rr}$	reverse recovery time	$I_F = 0.5 \text{ A}; I_R = 0.5 \text{ A}; I_{R(\text{meas})} = 0.1 \text{ A};$ $T_j = 25 \text{ }^\circ\text{C}$	-	2	-	ns
$V_{FRM}$	peak forward recovery voltage	$I_F = 0.5 \text{ A}; dI_F/dt = 20 \text{ A}/\mu\text{s}; T_j = 25 \text{ }^\circ\text{C}$	-	545	-	mV





$f = 1 \text{ MHz}; T_{\text{amb}} = 25 \text{ }^\circ\text{C}$

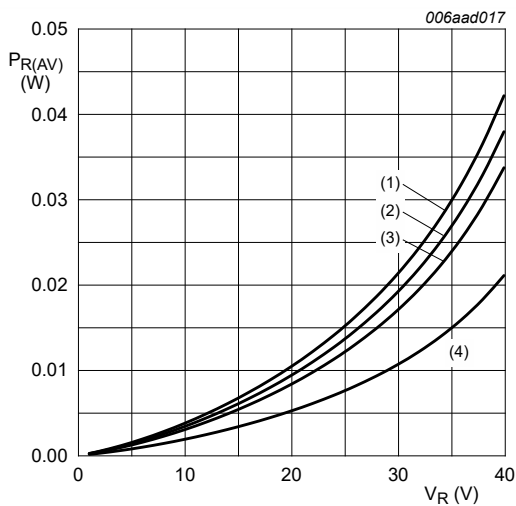
**Fig. 7. Diode capacitance as a function of reverse voltage; typical values**



$T_j = 150 \text{ }^\circ\text{C}$

- (1)  $\delta = 0.1$
- (2)  $\delta = 0.2$
- (3)  $\delta = 0.5$
- (4)  $\delta = 1$

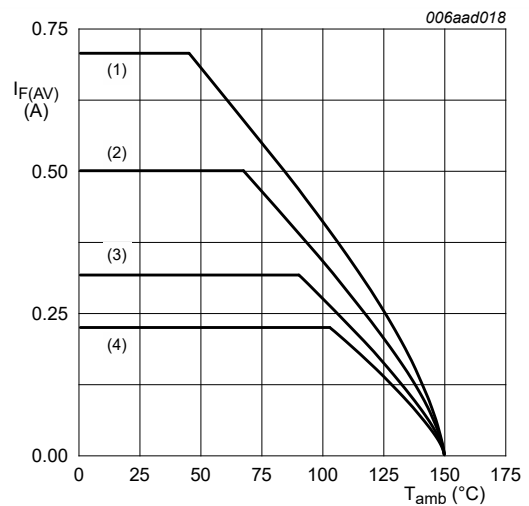
**Fig. 8. Average forward power dissipation as a function of average forward current; typical values**



$T_j = 125 \text{ }^\circ\text{C}$

- (1)  $\delta = 1$
- (2)  $\delta = 0.9$
- (3)  $\delta = 0.8$
- (4)  $\delta = 0.5$

**Fig. 9. Average reverse power dissipation as a function of reverse voltage; typical values**

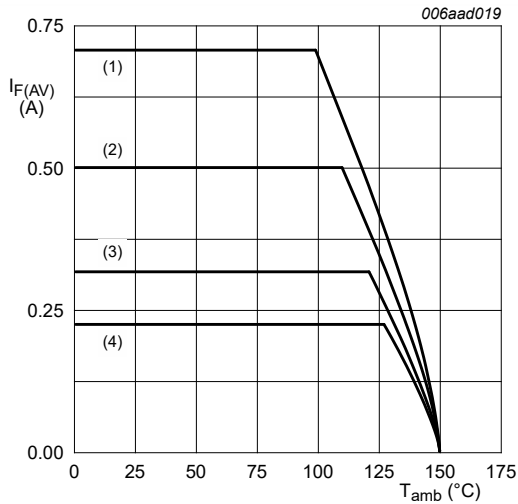


FR4 PCB, standard footprint

$T_j = 150 \text{ }^\circ\text{C}$

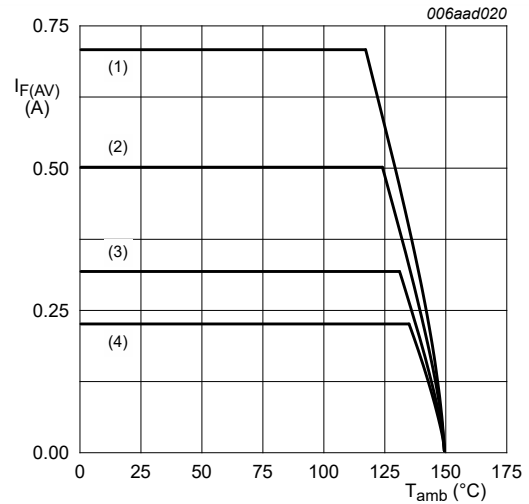
- (1)  $\delta = 1 \text{ (DC)}$
- (2)  $\delta = 0.5; f = 20 \text{ kHz}$
- (3)  $\delta = 0.2; f = 20 \text{ kHz}$
- (4)  $\delta = 0.1; f = 20 \text{ kHz}$

**Fig. 10. Average forward current as a function of ambient temperature; typical values**



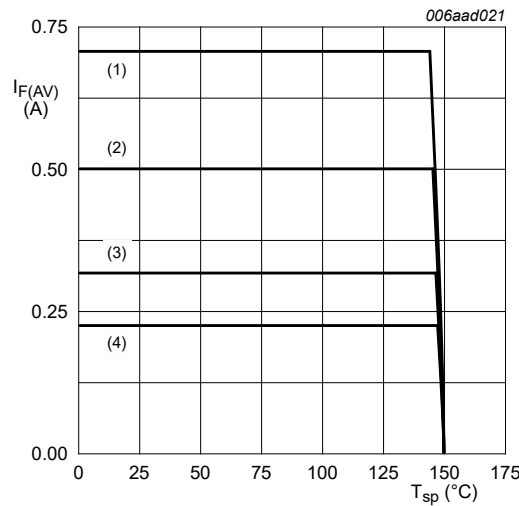
FR4 PCB, mounting pad for cathode 1 cm<sup>2</sup>  
 $T_j = 150\text{ °C}$   
 (1)  $\delta = 1$  (DC)  
 (2)  $\delta = 0.5$ ;  $f = 20\text{ kHz}$   
 (3)  $\delta = 0.2$ ;  $f = 20\text{ kHz}$   
 (4)  $\delta = 0.1$ ;  $f = 20\text{ kHz}$

**Fig. 11. Average forward current as a function of ambient temperature; typical values**



Ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint  
 $T_j = 150\text{ °C}$   
 (1)  $\delta = 1$  (DC)  
 (2)  $\delta = 0.5$ ;  $f = 20\text{ kHz}$   
 (3)  $\delta = 0.2$ ;  $f = 20\text{ kHz}$   
 (4)  $\delta = 0.1$ ;  $f = 20\text{ kHz}$

**Fig. 12. Average forward current as a function of ambient temperature; typical values**



$T_j = 150\text{ °C}$   
 (1)  $\delta = 1$  (DC)  
 (2)  $\delta = 0.5$ ;  $f = 20\text{ kHz}$   
 (3)  $\delta = 0.2$ ;  $f = 20\text{ kHz}$   
 (4)  $\delta = 0.1$ ;  $f = 20\text{ kHz}$

**Fig. 13. Average forward current as a function of solder point temperature; typical values**

### 11. Test information

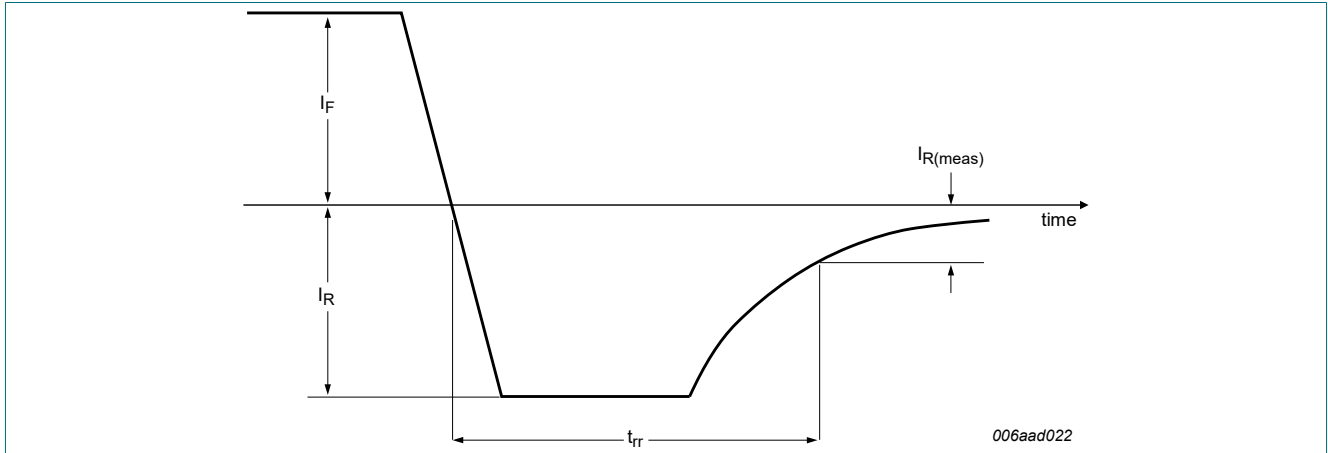


Fig. 14. Reverse recovery definition

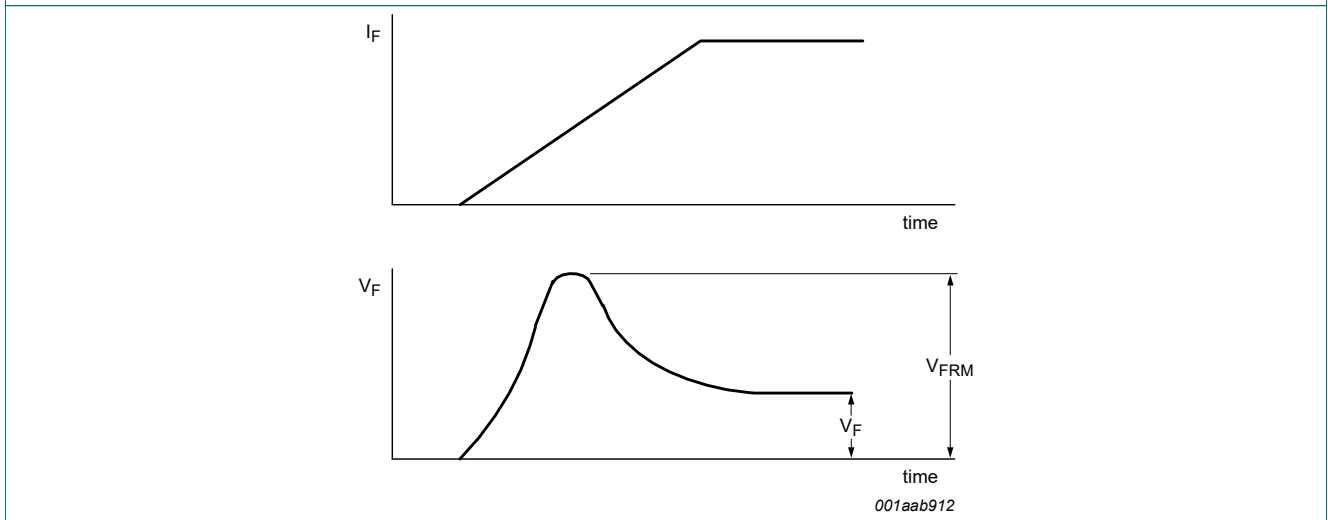


Fig. 15. Forward recovery definition

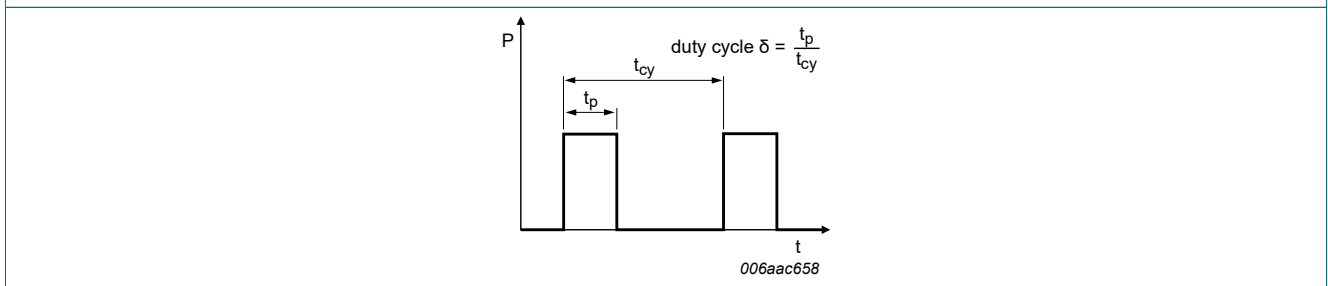


Fig. 16. Duty cycle definition

The current ratings for the typical waveforms are calculated according to the equations:  
 $I_{F(AV)} = I_M \times \delta$  with  $I_M$  defined as peak current,  $I_{RMS} = I_{F(AV)}$  at DC, and  $I_{RMS} = I_M \times \sqrt{\delta}$  with  $I_{RMS}$  defined as RMS current.

#### Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.



## 12. Package outline

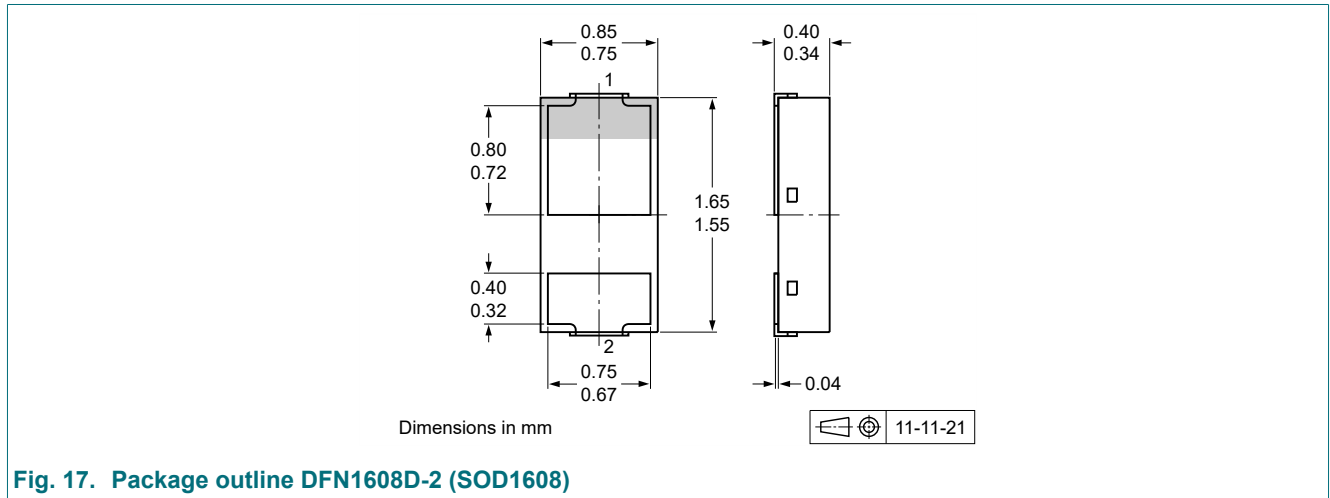


Fig. 17. Package outline DFN1608D-2 (SOD1608)

## 13. Soldering

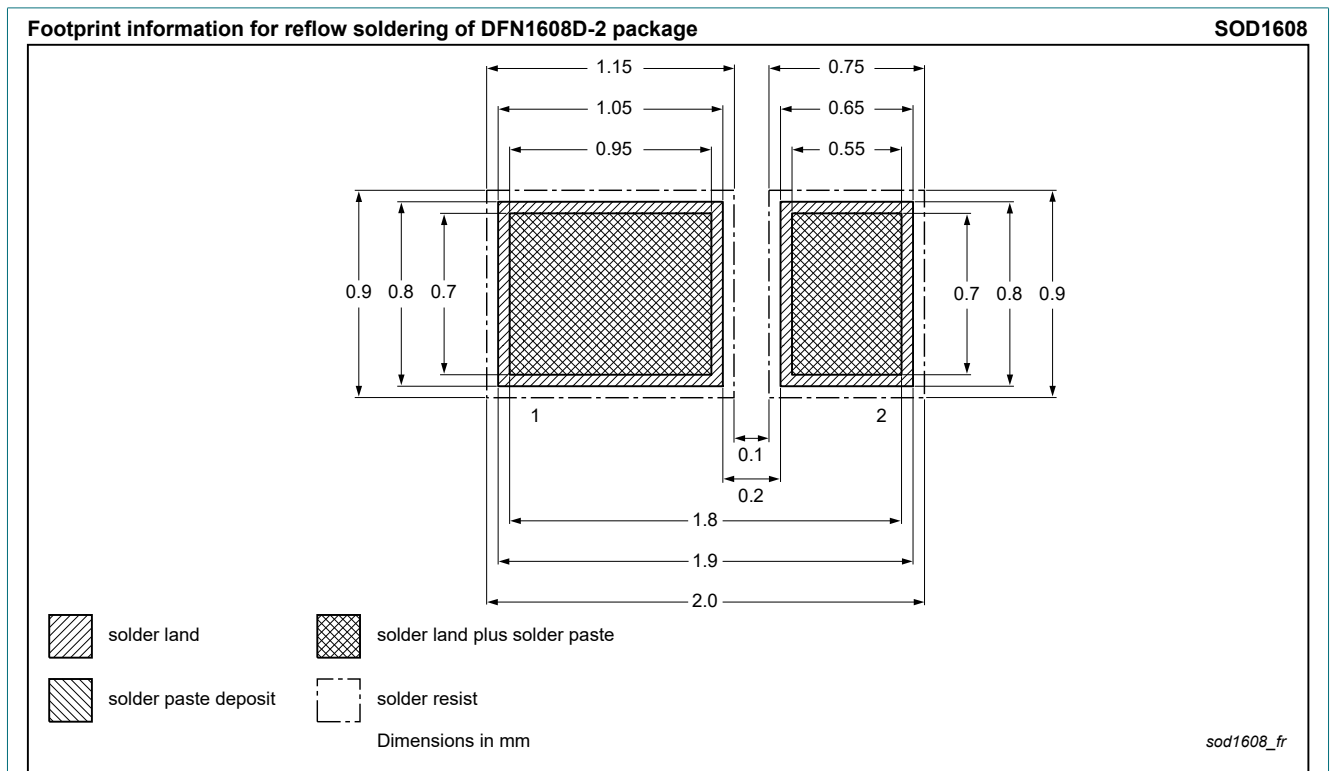


Fig. 18. Reflow soldering footprint for DFN1608D-2 (SOD1608)

## 14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PMEG4005EPK v.3	20200430	Product data sheet	-	PMEG4005EPK v.2
Modifications:	<ul style="list-style-type: none"><li>The format of this data sheet has been redesigned to comply with the identity guidelines of Nexperia.</li><li>Legal texts have been adapted to the new company name where appropriate.</li></ul>			
PMEG4005EPK v.2	20120306	Product data sheet	-	PMEG4005EPK v.1
PMEG4005EPK v.1	20120306	Product data sheet	-	-

## 15. Legal information

### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
- [3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the internet at <https://www.nexperia.com>.

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## Contents

---

1. General description.....	1
2. Features and benefits.....	1
3. Applications.....	1
4. Quick reference data.....	1
5. Pinning information.....	2
6. Ordering information.....	2
7. Marking.....	2
8. Limiting values.....	3
9. Thermal characteristics.....	3
10. Characteristics.....	5
11. Test information.....	8
12. Package outline.....	9
13. Soldering.....	9
14. Revision history.....	10
15. Legal information.....	11

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